# **1.0 A Output Current, Dual Power Operational Amplifiers**

The TCA0372 is a monolithic circuit intended for use as a power operational amplifier in a wide range of applications, including servo amplifiers and power supplies. No deadband crossover distortion provides better performance for driving coils.

### Features

- Output Current to 1.0 A
- Slew Rate of 1.3 V/µs
- Wide Bandwidth of 1.1 MHz
- Internal Thermal Shutdown
- Single or Split Supply Operation
- Excellent Gain and Phase Margins
- Common Mode Input Includes Ground
- Zero Deadband Crossover Distortion
- NCV devices are AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

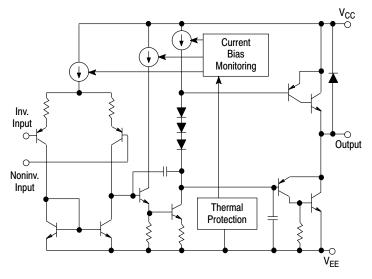
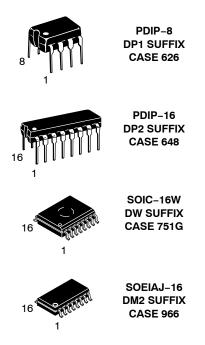


Figure 1. Representative Block Diagram



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#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 6 of this data sheet.

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Supply Voltage (from $V_{CC}$ to $V_{EE}$ )	V <sub>S</sub>	40	V
Input Differential Voltage Range	V <sub>IDR</sub>	Note 1	V
Input Voltage Range	V <sub>IR</sub>	Note 1	V
Junction Temperature (Note 2)	TJ	+150	°C
Operating Temperature Range	T <sub>A</sub>	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	–55 to +150	°C
DC Output Current	Ι <sub>Ο</sub>	1.0	А
Peak Output Current (Nonrepetitive)	I <sub>(max)</sub>	1.5	А
Thermal Resistance, Junction-to-Air Case 626 Case 648 Case 751G	R <sub>θJA</sub>	137 72 80	°C/W
Thermal Resistance, Junction-to-Case Case 626 Case 648 Case 751G	R <sub>θJC</sub>	23 10 12	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Either or both input voltages should not exceed the magnitude of  $V_{CC}$  or  $V_{EE}$ . 2. Power dissipation must be considered to ensure maximum junction temperature (T<sub>J</sub>) is not exceeded.

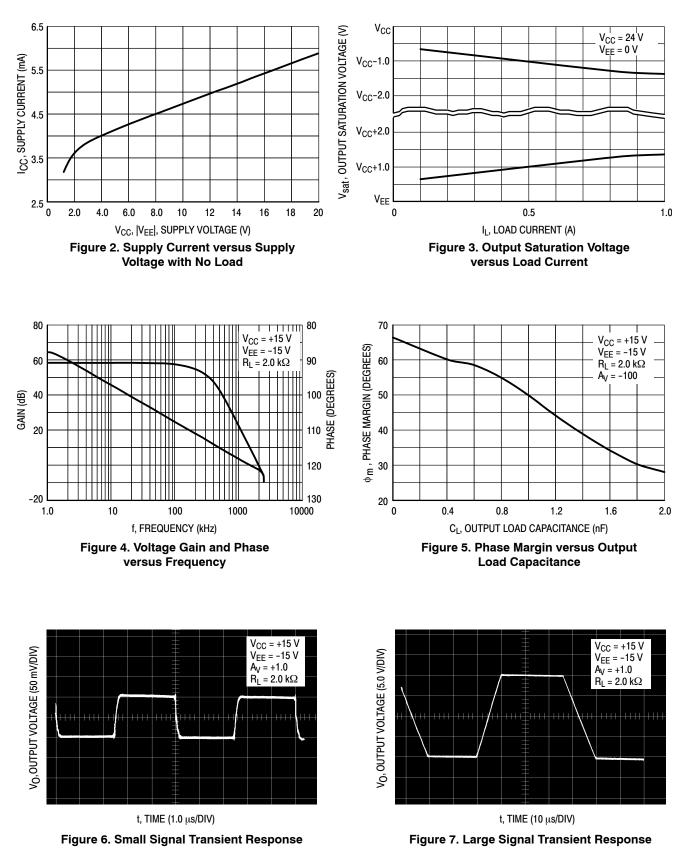
	Characteristics	Symbol	Min	Тур	Max	Unit
Input Offset Voltage (V <sub>CM</sub> T <sub>A</sub> = +25°C T <sub>A</sub> , T <sub>low</sub> to T <sub>high</sub>	= 0)	V <sub>IO</sub>		1.0 _	15 20	mV
Average Temperature Coe	fficient of Offset Voltage	$\Delta V_{IO} / \Delta T$	-	20	-	μV/°C
Input Bias Current (V <sub>CM</sub> =	0)	I <sub>IB</sub>	-	100	500	nA
Input Offset Current (V <sub>CM</sub>	= 0)	I <sub>IO</sub>	-	10	50	nA
Large Signal Voltage Gain $V_O = \pm 10 \text{ V}, \text{ R}_L = 2.0 \text{ k}$		A <sub>VOL</sub>	30	100	-	V/mV
$\begin{array}{l} Output Voltage Swing (I_L = $$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$	= 100 mA)	V <sub>OH</sub> V <sub>OL</sub>	14.0 13.9 - -	14.2 _ _14.2 _	- - -14.0 -13.9	V
$\begin{array}{l} \mbox{Output Voltage Swing (I_L = $V_{CC} = +24 \ V, \ V_{EE} = 0 \ V, $V_{CC} = 0 \ $	$T_A = +25^{\circ}C$ $T_A = T_{low}$ to $T_{high}$ $T_A = +25^{\circ}C$	V <sub>OH</sub> V <sub>OL</sub>	22.5 22.5 - -	22.7 - 1.3 -	- - 1.5 1.6	V
Input Common Mode Voltage Range $T_A = +25^{\circ}C$ $T_A = T_{low}$ to $T_{high}$		V <sub>ICR</sub>		to (V <sub>CC</sub> – to (V <sub>CC</sub> –		V
Common Mode Rejection	Ratio (R <sub>S</sub> = 10 k)	CMRR	70	90	-	dB
Power Supply Rejection Ratio ( $R_S = 100 \Omega$ )		PSRR	70	90	-	dB
$T_A = T_{low}$ to $T_{high}$ T	CA0372 CA0372B/NCV0372B CA0372 CA0372B/NCV0372B	۱ <sub>D</sub>	- - -	5.0 8.0 -	10 10 14 14	mA

### **DC ELECTRICAL CHARACTERISTICS** ( $V_{CC}$ = +15 V, $V_{EE}$ = -15 V, $R_L$ connected to ground, $T_A$ = -40° to +125°C.)

AC ELECTRICAL CHARACTERISTICS ( $V_{CC}$  = +15 V,  $V_{EE}$  = -15 V,  $R_L$  connected to ground,  $T_A$  = +25°C, unless otherwise noted.)

					,
Characteristics	Symbol	Min	Тур	Max	Unit
Slew Rate (V <sub>in</sub> = –10 V to +10 V, R <sub>L</sub> = 2.0 k, C <sub>L</sub> = 100 pF) $A_V$ = –1.0, T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub>	SR	1.0	1.4	-	V/μs
Gain Bandwidth Product (f = 100 kHz, C <sub>L</sub> = 100 pF, R <sub>L</sub> = 2.0 k) T <sub>A</sub> = 25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub>	GBW	0.9 0.7	1.4 -	-	MHz
Phase Margin $T_J = T_{low}$ to $T_{high}$ $R_L = 2.0 \text{ k}, C_L = 100 \text{ pF}$	φ <sub>m</sub>	-	65	-	Degrees
Gain Margin $R_L = 2.0 \text{ k}, C_L = 100 \text{ pF}$	A <sub>m</sub>	-	15	-	dB
Equivalent Input Noise Voltage $R_S = 100 \ \Omega$ , f = 1.0 to 100 kHz	e <sub>n</sub>	-	22	-	nV/√Hz
Total Harmonic Distortion $A_V = -1.0$ , $R_L = 50 \Omega$ , $V_O = 0.5$ VRMS, f = 1.0 kHz	THD	-	0.02	-	%

NOTE: In case V<sub>EE</sub> is disconnected before V<sub>CC</sub>, a diode between V<sub>EE</sub> and Ground is recommended to avoid damaging the device.



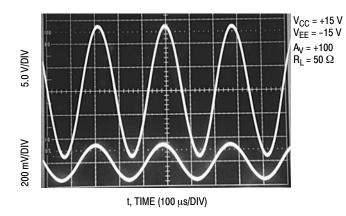


Figure 8. Sine Wave Response

V<sub>in</sub>

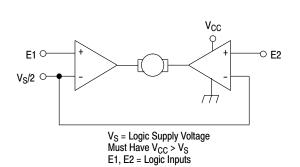


Figure 9. Bidirectional DC Motor Control with

#### **Microprocessor-Compatible Inputs** ٧<sub>S</sub> С R<sub>x</sub> 0.1 μF 0.1 μF **R**7 ≷ 10 k R1 ///~ 10 k R3 5.0 Ω R6 HR8 ≥ 10 k Ş 10 k R2 R5 h $\sim$ ∕∕∕∕ 10 k 10 k

For circuit stability, ensure that  $R_x > \frac{2R3 \cdot R1}{R_M}$  where,  $R_M$  = internal resistance of motor. The voltage available at the terminals of the motor is:  $V_M = 2(V_1 - \frac{V_S}{2}) + |R_0| \cdot I_M$ where,  $|R_0| = \frac{2R3 \cdot R1}{R_x}$  and  $I_M$  is the motor current.

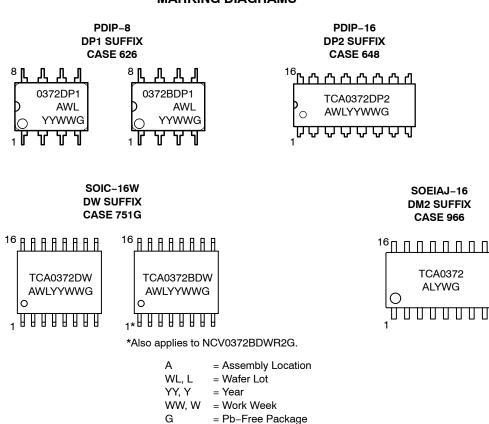
Figure 10. Bidirectional Speed Control of DC Motors

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
TCA0372DWG	SOIC-16W (Pb-Free)	47 Units / Rail
TCA0372DWR2G	SOIC-16W (Pb-Free)	1000 / Tape & Reel
TCA0372BDWR2G	SOIC-16W (Pb-Free)	1000 / Tape & Reel
NCV0372BDWR2G*	SOIC-16W (Pb-Free)	1000 / Tape & Reel
TCA0372DP1G	PDIP-8 (Pb-Free)	50 Units / Rail
TCA0372BDP1G	PDIP-8 (Pb-Free)	50 Units / Rail
TCA0372DP2G	PDIP-16 (Pb-Free)	25 Units / Rail
TCA0372DM2ELG	SOEIAJ-16 (Pb-Free)	2500 / Tape & Reel

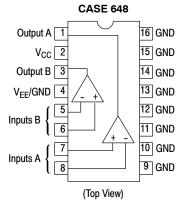
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

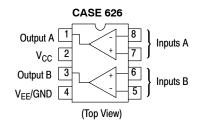
\*AEC-Q100 Qualified and PPAP Capable

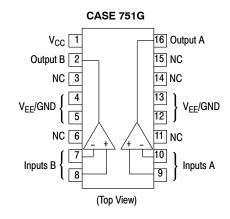


### **MARKING DIAGRAMS**

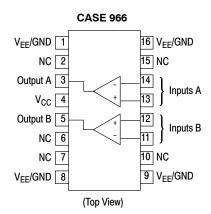
### **PIN CONNECTIONS**





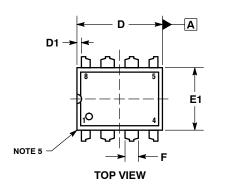


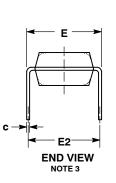
\*Pins 4 and 9 to 16 are internally connected.



### PACKAGE DIMENSIONS

PDIP-8 **DP1 SUFFIX** CASE 626-05 **ISSUE M** 



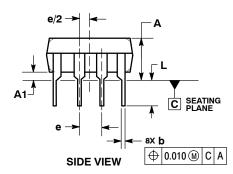


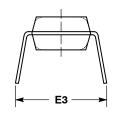
NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCHES.
 DIMENSION E IS MEASURED WITH THE LEADS RE-COTAINED PARALLEL AT WIDTH F2

STRAINED PARALLEL AT WIDTH E2. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH. ROUNDED CORNERS OPTIONAL. 4

5.

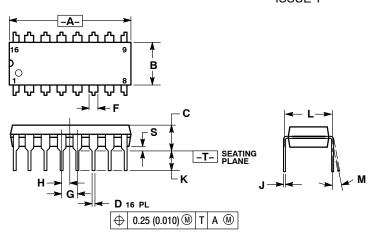
	INCHES			MILLIMETERS		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			0.210			5.33
A1	0.015			0.38		
b	0.014	0.018	0.022	0.35	0.46	0.56
С	0.008	0.010	0.014	0.20	0.25	0.36
D	0.355	0.365	0.400	9.02	9.27	10.02
D1	0.005			0.13		
E	0.300	0.310	0.325	7.62	7.87	8.26
E1	0.240	0.250	0.280	6.10	6.35	7.11
E2	0.300 BSC			7.62 BSC		
E3			0.430			10.92
e	(	0.100 BSC		2.54 BSC		;
L	0.115	0.130	0.150	2.92	3.30	3.81





**END VIEW** 

PDIP-16 **DP2 SUFFIX** CASE 648-08 ISSUE T



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 4. DIMENSION B DOES NOT INCLUDE MOLD ELASU

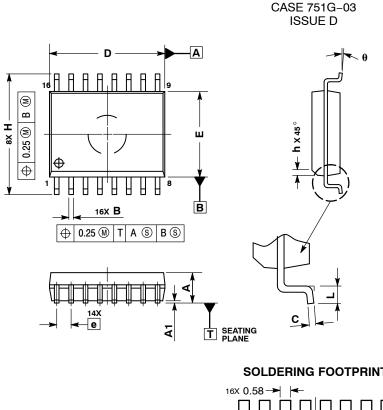
MOLD FLASH. ROUNDED CORNERS OPTIONAL.

5.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
н	0.050 BSC		1.27	BSC
J	0.008	0.015	0.21	0.38
К	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

### PACKAGE DIMENSIONS

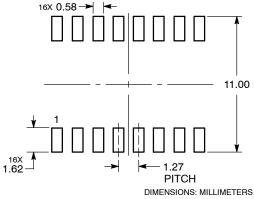
SOIC-16 WB

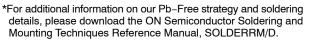


- NOTES:
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION. MATERIAL CONDITION.

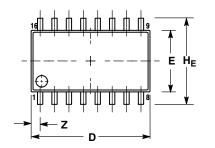
	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	10.15	10.45		
E	7.40	7.60		
е	1.27	BSC		
н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
q	0 °	7 °		

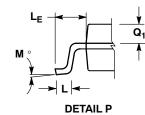
**SOLDERING FOOTPRINT\*** 

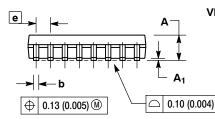


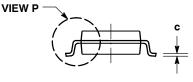


#### SOEIAJ-16 **DM2 SUFFIX CASE 966 ISSUE A**









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR
- PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN FORTO OF THE LEAD WIDTH LEAD WIDTH. 5 TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BS	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10 °	0 °	10 °
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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